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|-----------------------|-------------------------|-----------------------------------|------------|
| Number of Components: | Single | Minimum Bond Line Cure Schedule*: | |
| Mix Ratio By Weight: | N/A | 150°C | 30 Minutes |
| Specific Gravity: | 2.40 | 120°C | 60 Minutes |
| Part A | | | |
| Part B | | | |
| Pot Life: | 25 Days | | |
| Shelf Life: | Six months refrigerated | | |

Note: Container(s) should be kept closed when not in use. Mix contents thoroughly prior to use. *Please see Applications Note available on our website.

Product Description:

EPO-TEK[®] H61 is a single component, thermally conductive, electrically insulating, epoxy adhesive for semiconductor, hybrid IC, and electronic circuit assembly applications.

EPO-TEK[®] H61 Advantages & Application Notes:

- It is a thixotropic paste and a non-sagging adhesive. It is also useful for deposition methods like dispensing, printing, or hand held processes.
- Suggested Applications:
 - Hybrid:
 - Staking SMDs onto the PCB for extra mechanical support; insulation layer between 2 contact pads of caps and resistors.
 - Heat sinking devices on ceramic PCB and PCB to external case; adhesion to Si, Au, kovar, Al-N, BT.
 - Reinforcing and extra mechanical support for wire bond integrity.
 - Electronics:
 - Bonding passive devices such as inductor coils, ferrites, motors, connectors, and various SMDs.
 - Adhesion to FR4 and common PCB substrates and housings.
- Available in various viscosity alternatives and black color. Contact techserv@epotek.com for your best recommendation.

Typical Properties: (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour ; * denotes test on lot acceptance basis)

| Physical Properties: | |
|--|--|
| *Color: Grayish White | Weight Loss: |
| *Consistency: Smooth paste | @ 200°C: 0.08% |
| *Viscosity (@ 5 RPM/23°C): 40,000 – 60,000cPs | @ 250°C: |
| Thixotropic Index: 1.32 | @ 300°C: |
| *Glass Transition Temp.(Tg): ≥ 110°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min) | Operating Temp: |
| Coefficient of Thermal Expansion (CTE): | Continuous: - 55°C to 200°C |
| Below Tg: 17 x 10 ⁻⁶ in/in/°C | Intermittent: - 55°C to 300°C |
| Above Tg: 95 x 10 ⁻⁶ in/in/°C | Storage Modulus @ 23°C: 791,294 psi |
| Shore D Hardness: 89 | Ions: Cl ⁻ 41 ppm |
| Lap Shear Strength @ 23°C: 1,144 psi | Na ⁺ 140 ppm |
| Die Shear Strength @ 23°C: ≥20 Kg / 6,800 psi | NH ₄ ⁺ 354 ppm |
| Degradation Temp. (TGA): 425°C | K ⁺ 0 ppm |
| | *Particle Size: ≤ 50 Microns |
| Thermal Properties: | |
| Thermal Conductivity: 0.70 W/mK | |
| Electrical Properties: | |
| Dielectric Constant (1KHz): 4.75 | Volume Resistivity @ 23°C: ≤ 2 x 10 ¹³ Ohm-cm |
| Dissipation Factor (1KHz): 0.006 | |

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